



TO-252-2L Plastic-Encapsulate MOSFETS

CCM060N04NTF N-Channel Power MOSFET

| V_{DS} | $R_{DS(ON)}$ (Typ.) | I_D |
|----------|---------------------|-------|
| 40V | 4.8m Ω @10V | 70A |

DESCRIPTION

The CCM060N04NTF provides excellent $R_{DS(ON)}$ with low gate charge.

It can be used in a wide variety of applications.

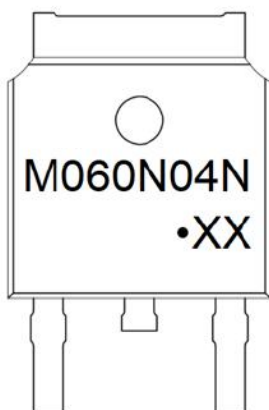
FEATURES

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

APPLICATIONS

- Power switching application

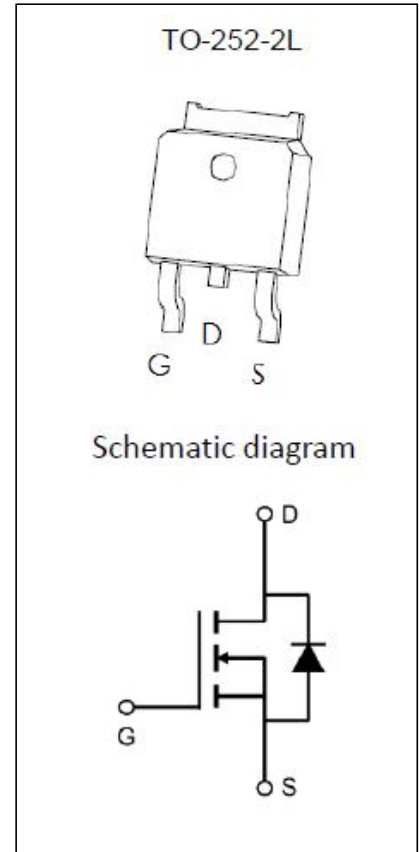
MARKING



M060N04N = Device Code

XX = Date Code

Solid Dot = Green Indicator



ABSOLUTE MAXIMUM RATINGS(T_a=25°C unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|--|------------------------|----------------|---------|
| Drain - Source Voltage | V _{DS} | 40 | V |
| Gate - Source Voltage | V _{GS} | ±20 | V |
| Continuous Drain Current ¹ | T _C = 25°C | I _D | 70 A |
| | T _C = 100°C | I _D | 55 A |
| Pulsed Drain Current ² | I _{DM} | 280 | A |
| Single Pulsed Avalanche Current ³ | I _{AS} | 20.5 | A |
| Single Pulsed Avalanche Energy ³ | E _{AS} | 105 | mJ |
| Power Dissipation ⁵ | T _C = 25°C | P _D | 42 W |
| Thermal Resistance from Junction to Ambient ⁶ | R _{θJA} | 53 | °C/W |
| Thermal Resistance from Junction to Case | R _{θJC} | 3 | °C/W |
| Junction Temperature | T _J | 150 | °C |
| Storage Temperature | T _{STG} | -55~ +150 | °C |

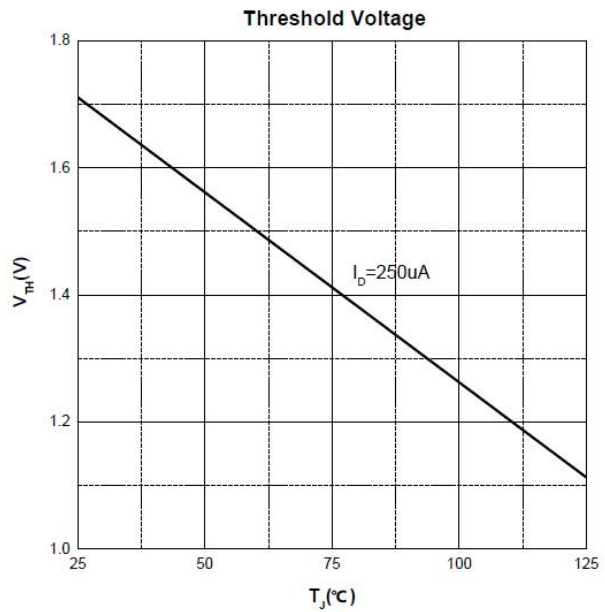
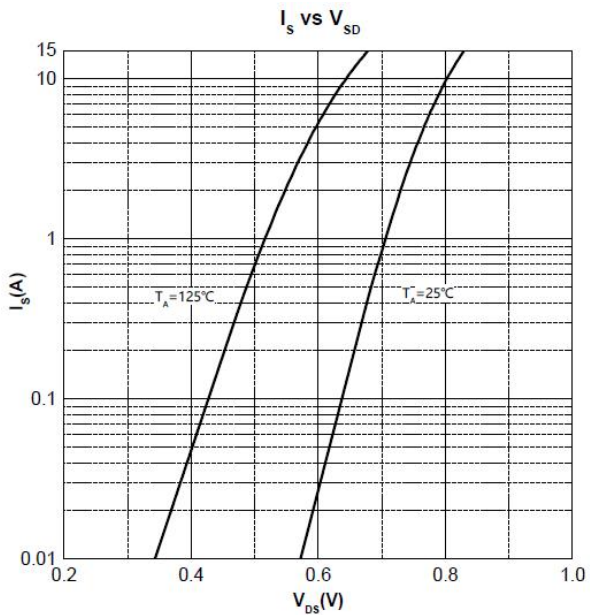
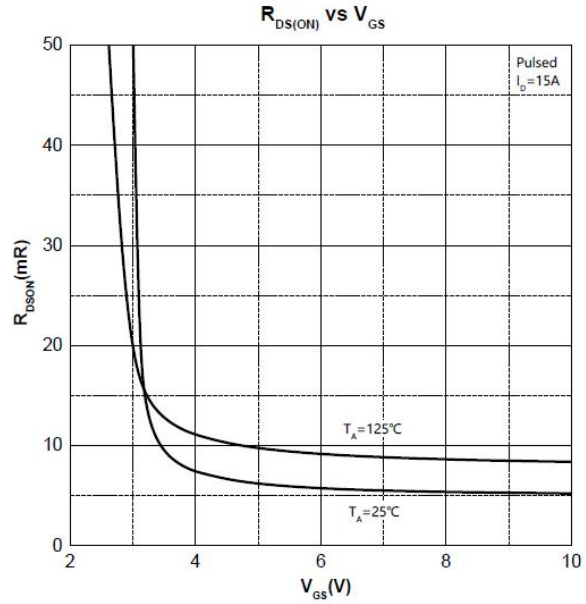
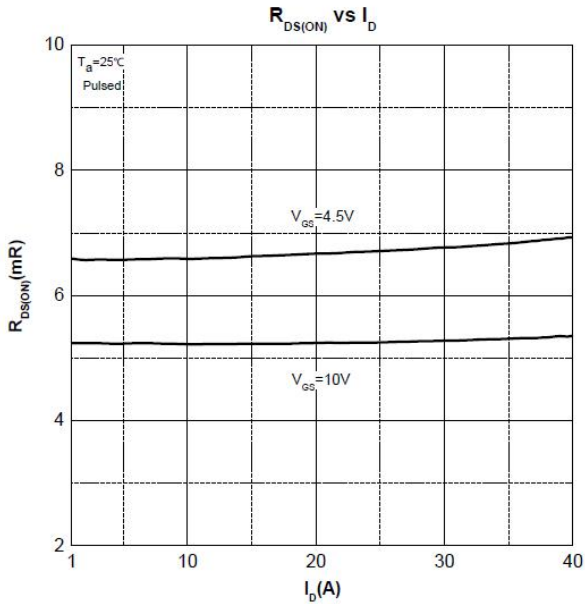
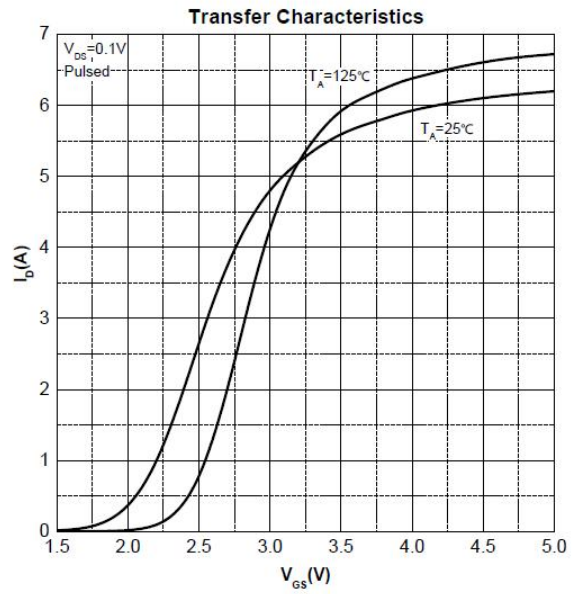
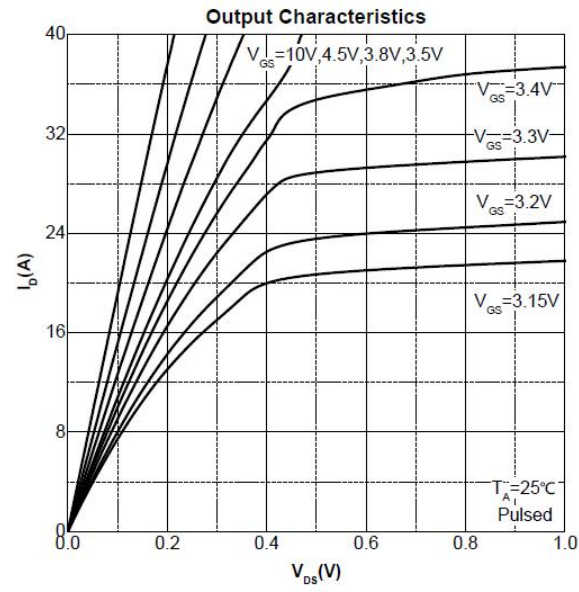
MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

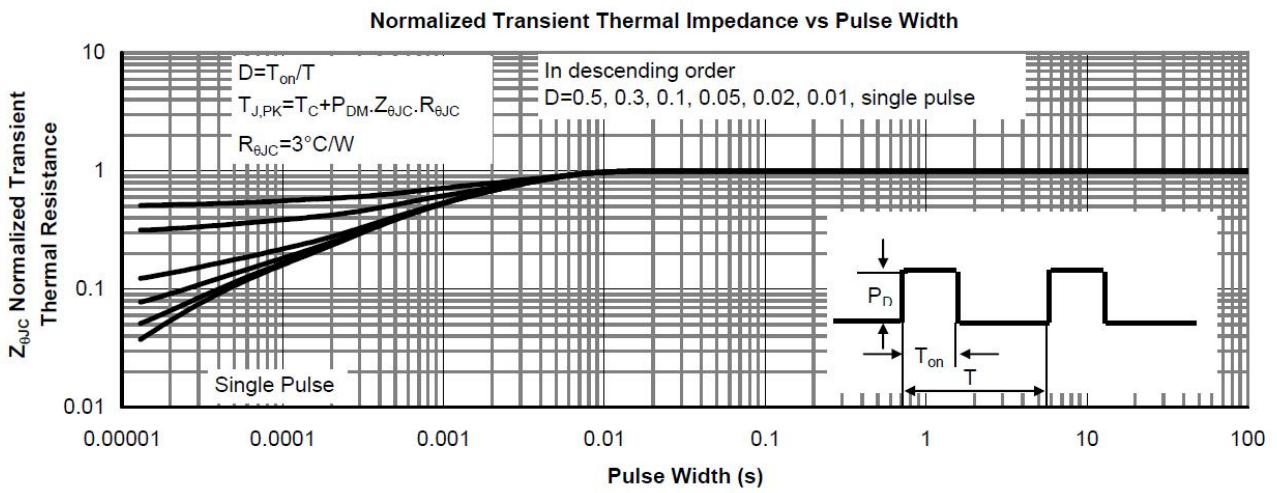
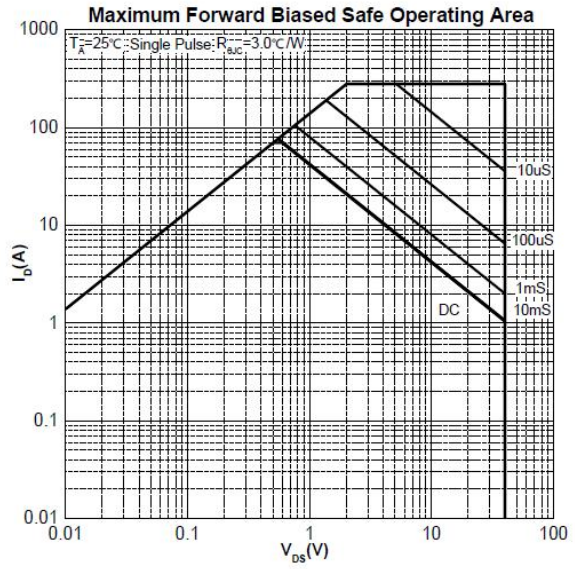
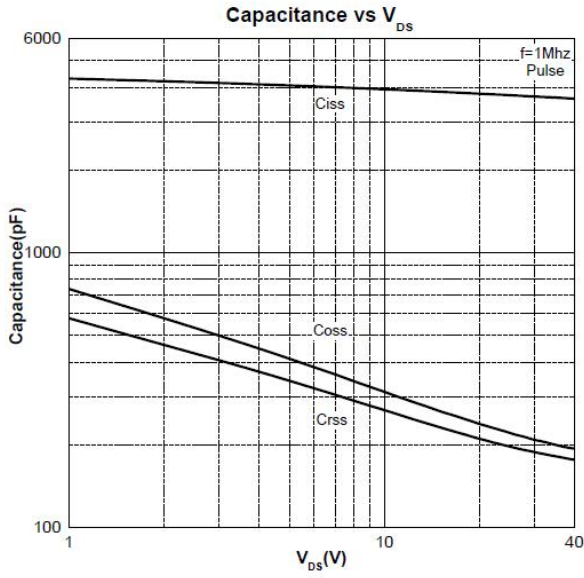
| Parameter | Symbol | Test Condition | Min | Type | Max | Unit |
|---|----------------------|--|-----|------|------|------|
| Off Characteristics | | | | | | |
| Drain - Source Breakdown Voltage | V _{(BR)DSS} | V _{GS} = 0V, I _D = 250μA | 40 | | | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 40V, V _{GS} = 0V | | | 1 | μA |
| Gate - Body Leakage Current | I _{GSS} | V _{GS} = ±20V, V _{DS} = 0V | | | ±100 | nA |
| On Characteristics⁴ | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250μA | 1.0 | 1.7 | 3.0 | V |
| Drain-source On-resistance | R _{DS(on)} | V _{GS} = 10V, I _D = 15A | | 4.8 | 6.2 | mΩ |
| | | V _{GS} = 4.5V, I _D = 10A | | 5.6 | 8.5 | |
| Forward Transconductance | g _{FS} | V _{DS} = 5V, I _D = 5A | | 36 | | S |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} = 20V, V _{GS} = 0V, f = 1MHz | | 3747 | | pF |
| Output Capacitance | C _{oss} | | | 238 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 210 | | |
| Gate Resistance | R _g | V _{DS} = 0V, V _{GS} = 0V, f = 1MHz | | 1.9 | | Ω |
| Switching Characteristics | | | | | | |
| Total Gate Charge | Q _g | V _{DS} = 20V, V _{GS} = 10V, I _D = 15A | | 67 | | nC |
| Gate-source Charge | Q _{gs} | | | 9.6 | | |
| Gate-drain Charge | Q _{gd} | | | 12 | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} = 20V, V _{GS} = 10V, R _L = 1Ω R _G = 3Ω | | 7 | | ns |
| Turn-on Rise Time | t _r | | | 15 | | |
| Turn-off Delay Time | t _{d(off)} | | | 31 | | |
| Turn-off Fall Time | t _f | | | 17 | | |
| Source - Drain Diode Characteristics | | | | | | |
| Diode Forward Voltage ⁴ | V _{SD} | V _{GS} = 0V, I _S = 15A | | | 1.2 | V |
| Diode Reverse Recovery Time | t _{rr} | I _F = 20A, dI/dt = 100A/μs | | 25 | | ns |
| Diode Reverse Recovery Charge | Q _{rr} | I _F = 20A, dI/dt = 100A/μs | | 30 | | nC |

Notes :

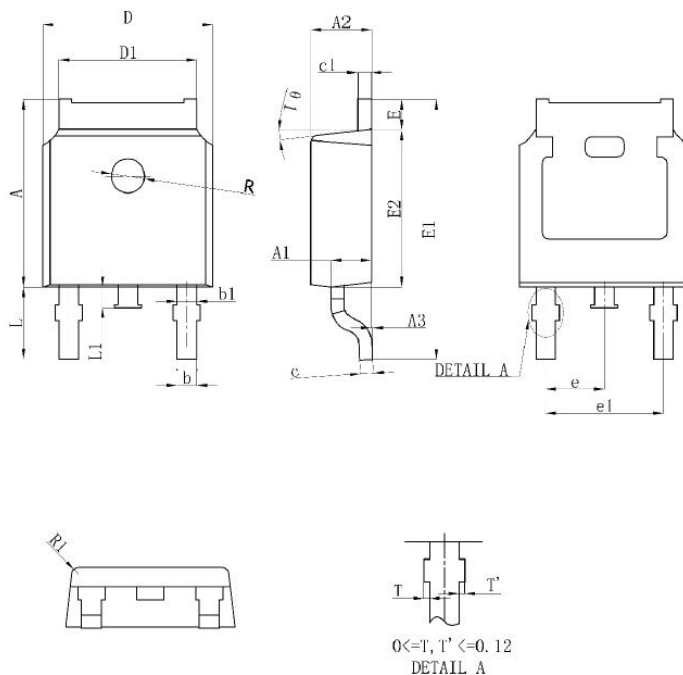
1. The maximum current rating is limited by package. And device mounted on a large heatsink.
2. Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
3. EAS condition: $V_{DD} = 20\text{V}$, $V_{GS} = 10\text{V}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
4. Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
5. The power dissipation PD is limited by $T_J(\text{MAX}) = 150^\circ\text{C}$. And device mounted on a large heatsink.
6. Device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Characteristics Curve:





TO-252 Package Outline Dimensions



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 7.050 | 7.150 | 0.278 | 0.281 |
| A1 | 0.960 | 1.060 | 0.038 | 0.042 |
| A2 | 2.200 | 2.400 | 0.087 | 0.094 |
| A3 | 0.000 | 0.100 | 0.000 | 0.004 |
| b | 0.760REF | | 0.030REF | |
| b1 | 1.000REF | | 0.039REF | |
| c | 0.508REF | | 0.020REF | |
| c1 | 0.508REF | | 0.020REF | |
| D | 6.550 | 6.650 | 0.258 | 0.262 |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 |
| E | 0.950 | 1.050 | 0.037 | 0.041 |
| E1 | 9.700 | 10.400 | 0.382 | 0.409 |
| E2 | 6.000 | 6.200 | 0.236 | 0.244 |
| e | 2.286BSC | | 0.090BSC | |
| e1 | 4.572REF | | 0.180REF | |
| L | 2.650 | 2.950 | 0.104 | 0.116 |
| L1 | 0.700 | 0.900 | 0.028 | 0.035 |
| theta | 7°REF | | 7°REF | |
| R | 1.300REF | | 0.051REF | |
| R1 | 0.250REF | | 0.010REF | |

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| Date of change | Rev # | revise content |
|----------------|-------|----------------|
| 2023/07/24 | A/0 | / |
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